ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under b international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IDC Web Site for Information on IDC 1752 Standard				Form Type 'Distribute										
Supplier	· Information														
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*			
onsemi											2024-05	2024-05-17			
Contact Name			Title - Conta	Title - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-E	Env-Stewards		Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative				Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		n Number	Number Mfr Item Name			Effective Date	Version	Ma	Manufacturing Site		Weight*	UOM	Unit Type	
	NC7S08I		BP5X-F22057	PSX-F22057 HS 2-Input AND Gate. Related FPCN22057. For customers who accept the PCN.			2024-05-17		CN	CNS		5.9997	mg	Each	
Manufacturing Process Information															
Terminal Plating / Grid Array Material T			Terminal Base Alloy J-STD		J-STD-020 MSL	Rating	Peak Proce	ess Body Ter	ss Body Temperature   Max Time at Peak		ak Tempera	Temperature Number of I		cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С	30 sec		seconds 3			
Comments															
level 1 - maximum time at peak temperature during soldering is 10-30 seconds															
For more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2027	mg	Supplier	Silicon (Si)	7440-21-3		0.2027	mg
Die Attach	0.0202	mg	Supplier	Silver (Ag)	7440-22-4		0.0162	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.004	mg
Lead Frame	3.2956	mg	Supplier	Zinc (Zn)	7440-66-6		0.0042	mg
			Supplier	Iron (Fe)	7439-89-6		0.0781	mg
			Supplier	Copper (Cu)	7440-50-8		3.2106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0027	mg
Mold Compound-Black	2.4264	mg		Epoxy resin	proprietary data		0.1213	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0485	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.0607	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0121	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.1838	mg
Plating	0.0244	mg	Supplier	Palladium (Pd)	7440-05-3		0.001	mg
			В	Nickel (Ni)	7440-02-0		0.0232	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
Wire Bond - Au	0.0304	mg	Supplier	Gold (Au)	7440-57-5		0.0304	mg